



## PRODUCT DATA SHEET



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**Datasheet**



**Resources**

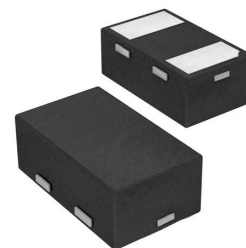


**Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

## Features

- 100Watts peak pulse power ( $t_p = 8/20\mu s$ )
- Tiny DFN1006 package
- Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance ( $C_j = 0.25pF$  typ. IO to IO)
- Protection one data/power line to:
- IEC 61000-4-2  $\pm 20kV$  contact  $\pm 20kV$  air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4A (8/20 $\mu s$ )



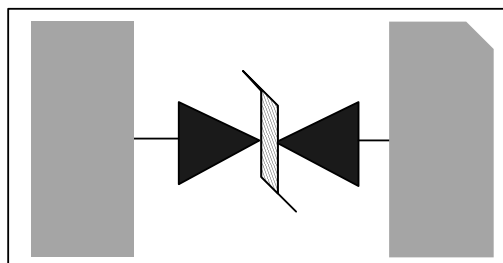
## Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation

## Mechanical Data

- DFN1006 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

## Schematic & PIN Configuration



**DFN1006**

### Absolute Maximum Rating

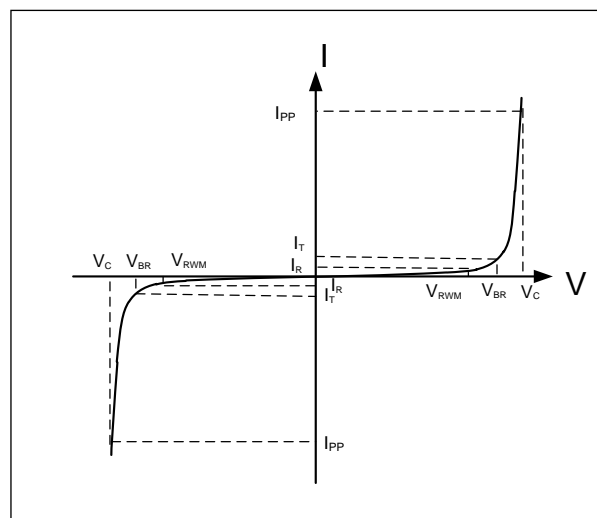
Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{PP}$	100	Watts
Peak Pulse Current ( $t_p = 8/20\mu s$ ) (note1)	$I_{PP}$	4.0	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	20 20	kV
Lead Soldering Temperature	$T_L$	260(10seconds)	°C
Junction Temperature	$T_J$	-55 to + 125	°C
Storage Temperature	$T_{stg}$	-55 to + 125	°C

### Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{RWM}$				5.0	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T = 1mA$	6.0			V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5V, T = 25^\circ C$			100	nA
Peak Pulse Current	$I_{PP}$	$t_p = 8/20\mu s$			4.0	A
Clamping Voltage	$V_C$	$I_{PP} = 4A, t_p = 8/20\mu s$			25	V
Junction Capacitance	$C_j$	IO to IO $V_R = 0V, f = 1MHz$		0.25	0.4	pF

### Electrical Parameters (TA = 25 °C unless otherwise noted)

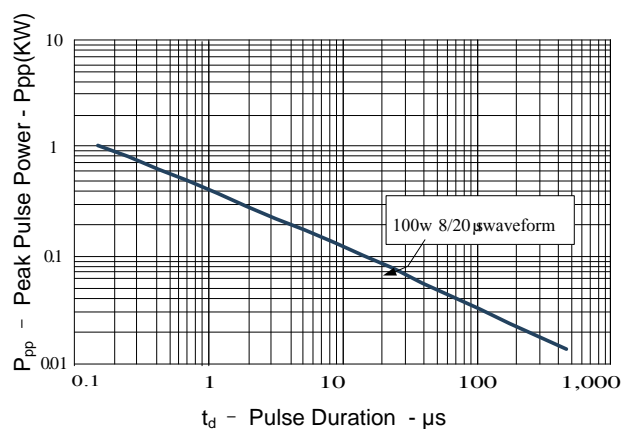
Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current



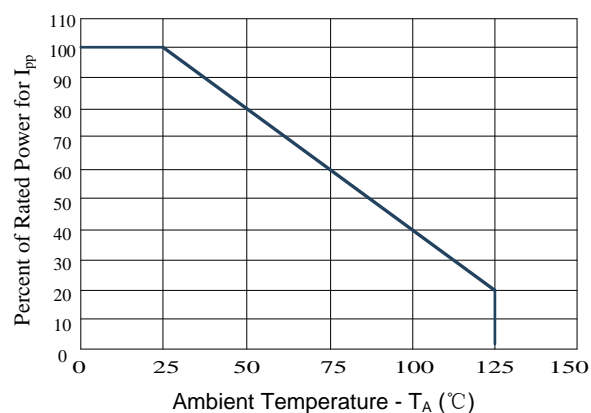
Note: 8/20 $\mu s$  pulse waveform.

## Typical Characteristics

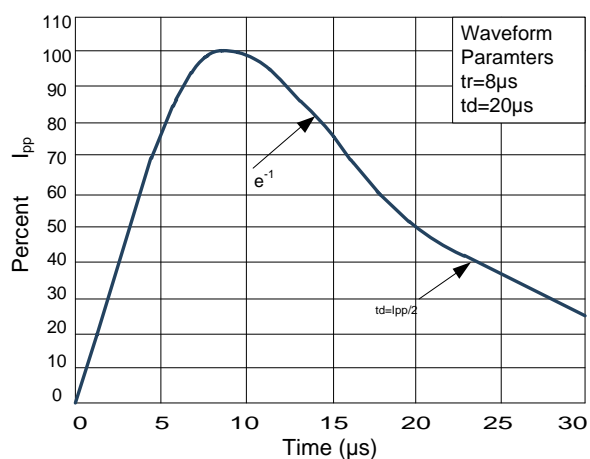
**Figure 1: Peak Pulse Power vs. Pulse Time**



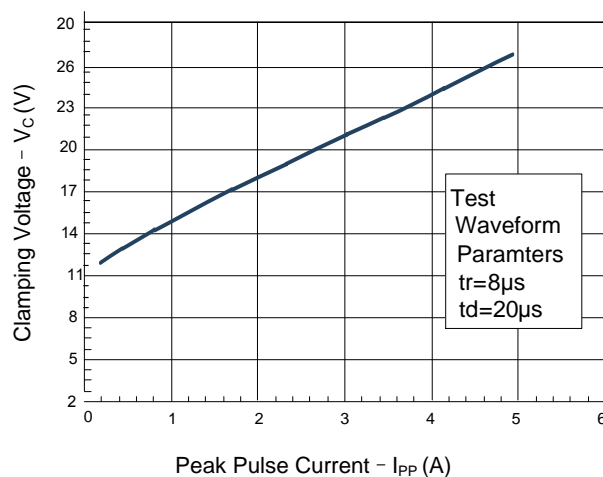
**Figure 2: Power Derating Curve**



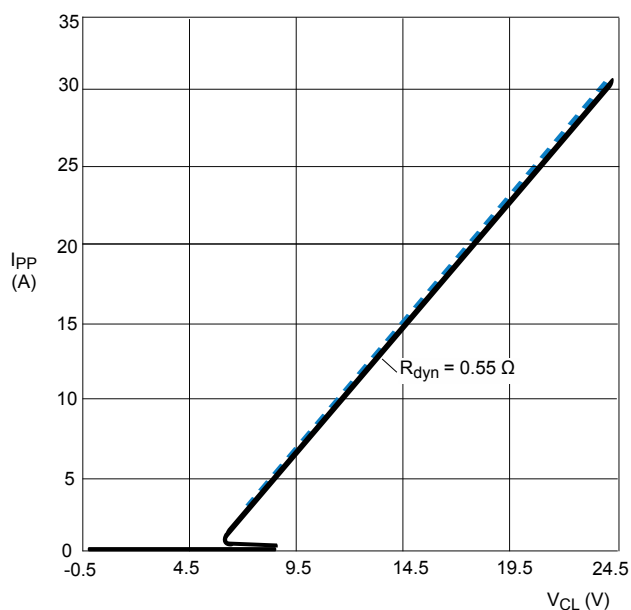
**Figure3: Pulse Waveform**



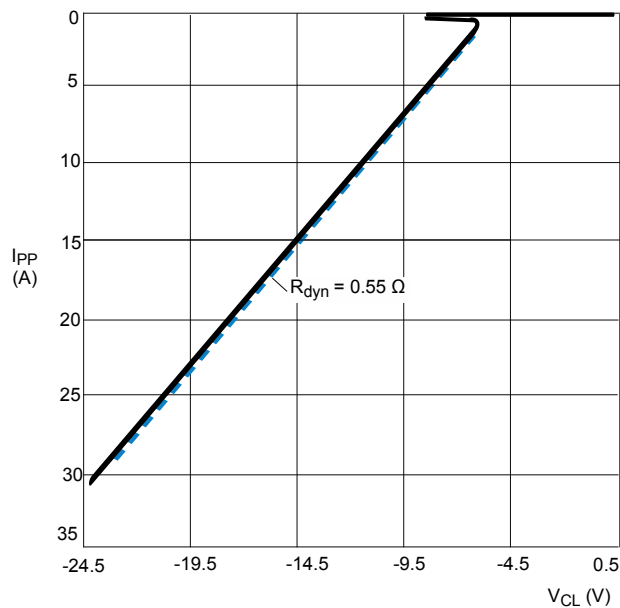
**Figure 4: Clamping Voltage vs. Ipp**



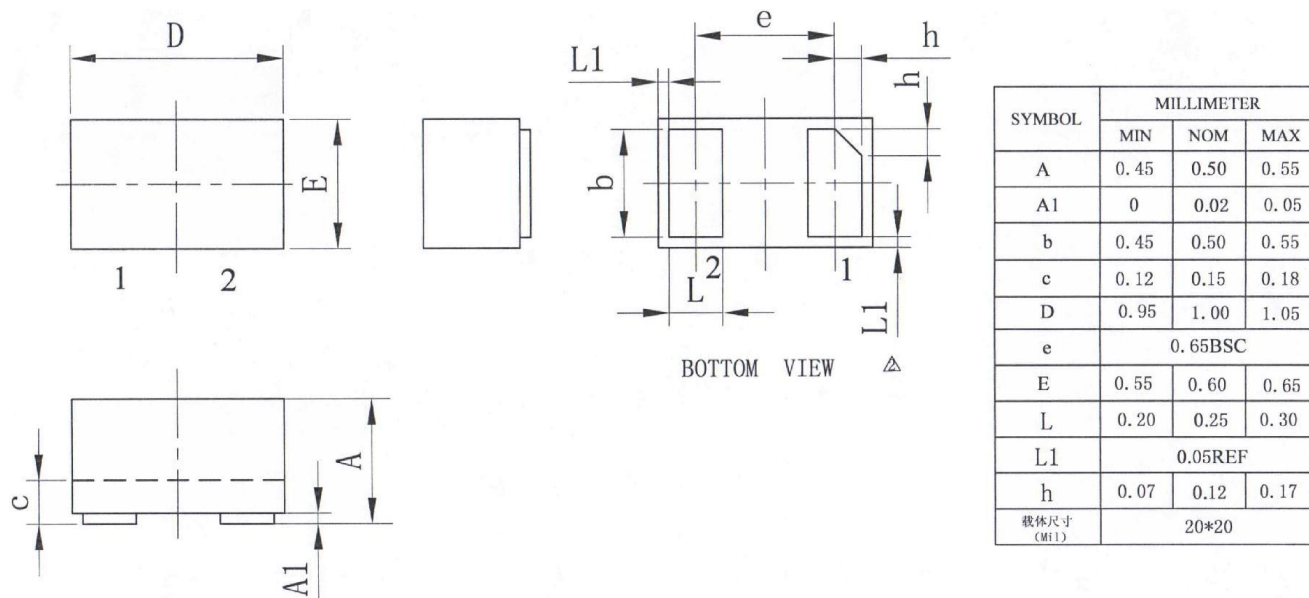
**Figure5: Positive Clamping voltage (TLP)**



**Figure5: Negative Clamping voltage (TLP)**



## Outline Drawing – DFN1006



## Marking



## Ordering information

Order code	Package	Base qty	Delivery mode
PESDUC2FD5VB	DFN1006	10k	Tape and reel

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